Specification of Electret Condenser Microphone

(RoHS Compliance&Halogen-Free)

Customer Name：

Customer Model：

GoerTek Model： B4013AM423-092

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Restricted

1 Security warning

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2 Publication history

Version	Date	Description	Design	Approval
1.0	2017.04.01	New Design	Lein	Near

3 Symbols Show

Symbols	Show
©	Signify Customer's Special Characteristic.
Ⓖ	Signify GoerTek Special Characteristic.

Contents

PRODUCT SPECIFICATIONS

Type: Electret Condenser Microphone
Number: B4013AM423-092

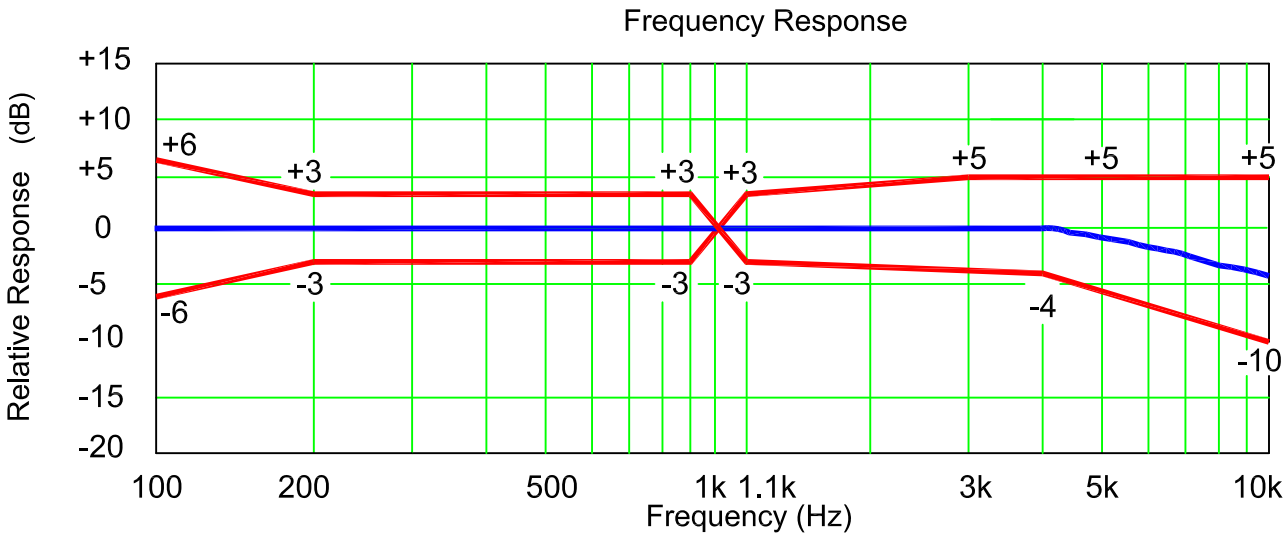
1 Test Condition (Vs=2.0V , RL=2.2kΩ, L= 50 cm)

StandardConditions (As IEC 60268-4)	Temperature	Humidity	Air pressure
Environment Conditions	+15℃～+35℃	25％RH～75%RH	86kPa～106kPa
Basic Test Conditions	+20℃±2℃	60％RH～70%RH	86kPa～106kPa

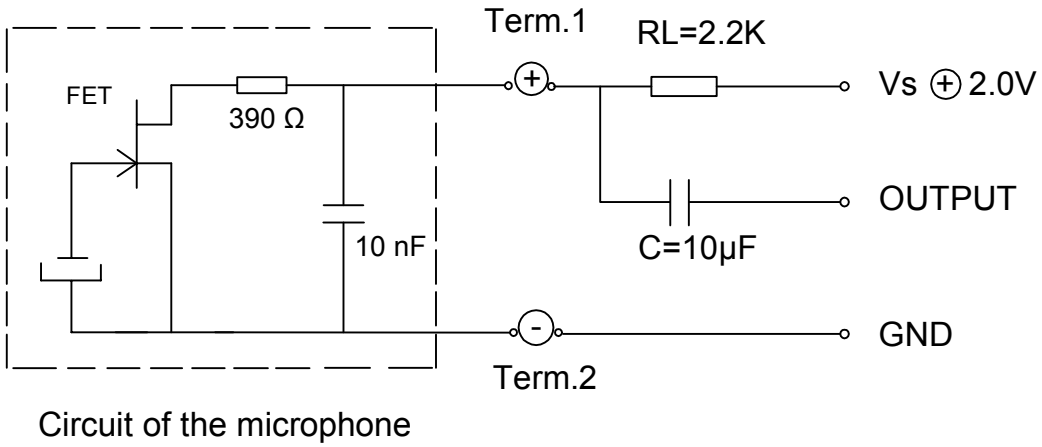
2 Electrical Characteristics

Item	Symbol	Test Conditions	Min	Standard	Max	Unit
Sensitivity	S	f=1kHz, Pin=1Pa	-45	-42	-39	dB 0dB=1V/Pa
Output Impedance	Zout	f=1kHz, Pin=1Pa			2.2k	Ω
Directivity	D(θ)	Omnidirectional				dB
Current Consumption	I				500	μA
S/N Ratio	S/N(A)	f=1kHz, Pin=1Pa A-Weighted Curve	58			dB
Decreasing Voltage Characteristic	ΔS	f=1kHz, Pin=1Pa Vs=2.0--1.5V			-3	dB
Operating Voltage Range	Vs		1.0		10	V
Distortion	THD	f=1kHz, Pin=104dB			3	%

3 Frequency Response Curve and Limits

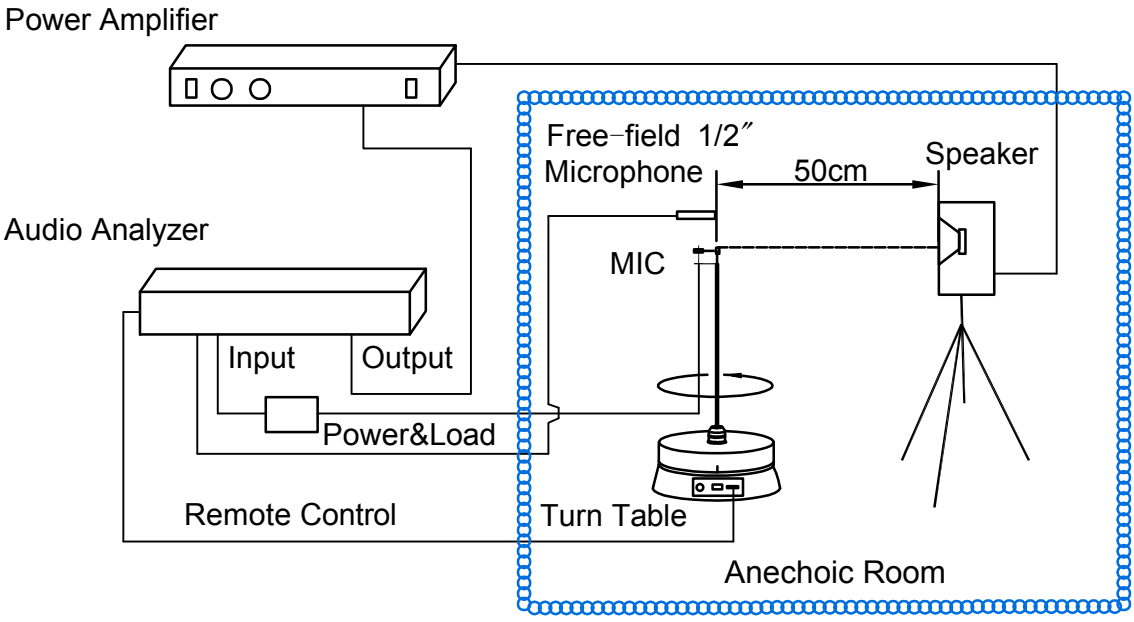


4 Measurement Circuit



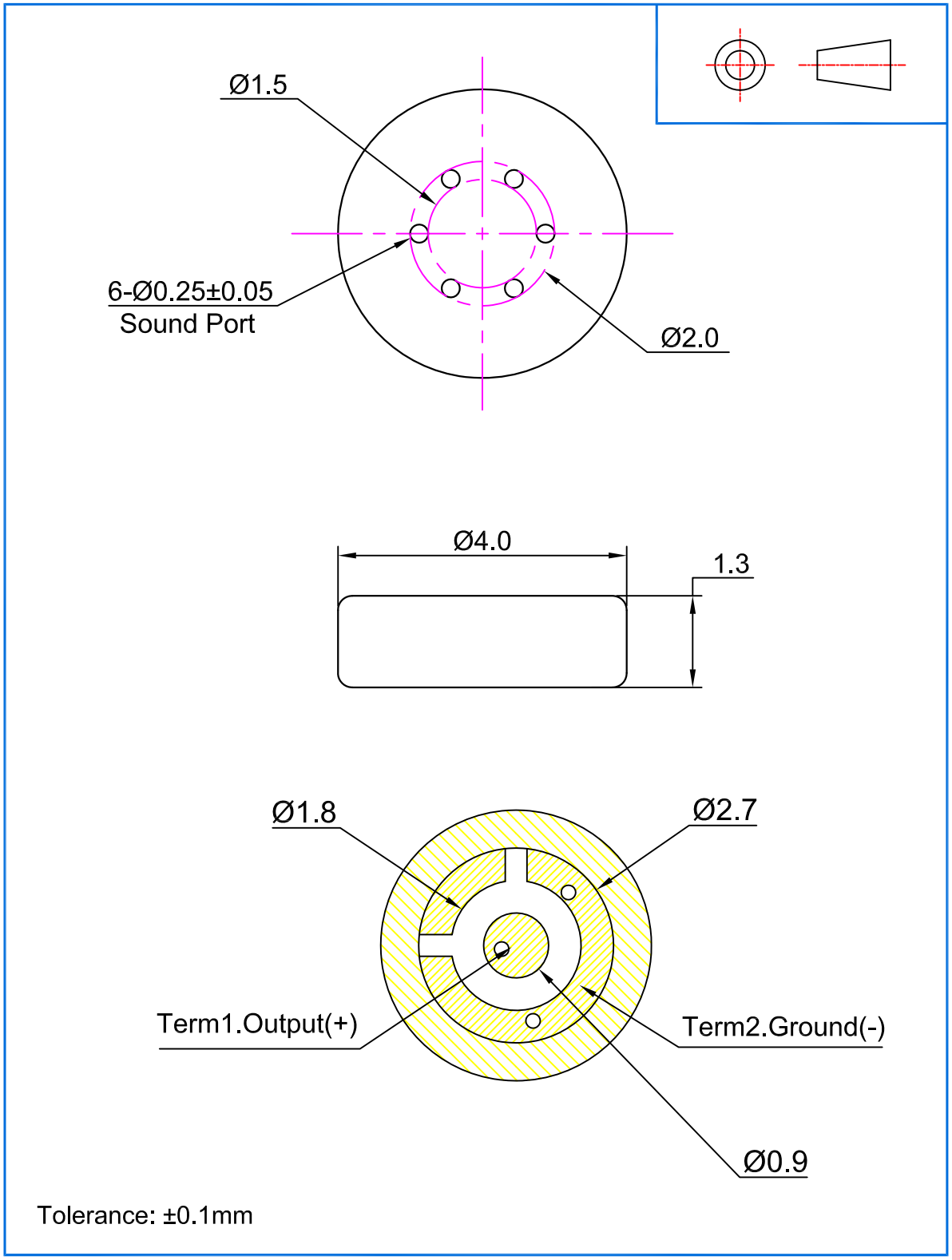
Circuit of the microphone

5 Test setup Drawing



6 Mechanical Characteristics

6.1 Appearance Drawing(Unit: mm)



6.2 Weight

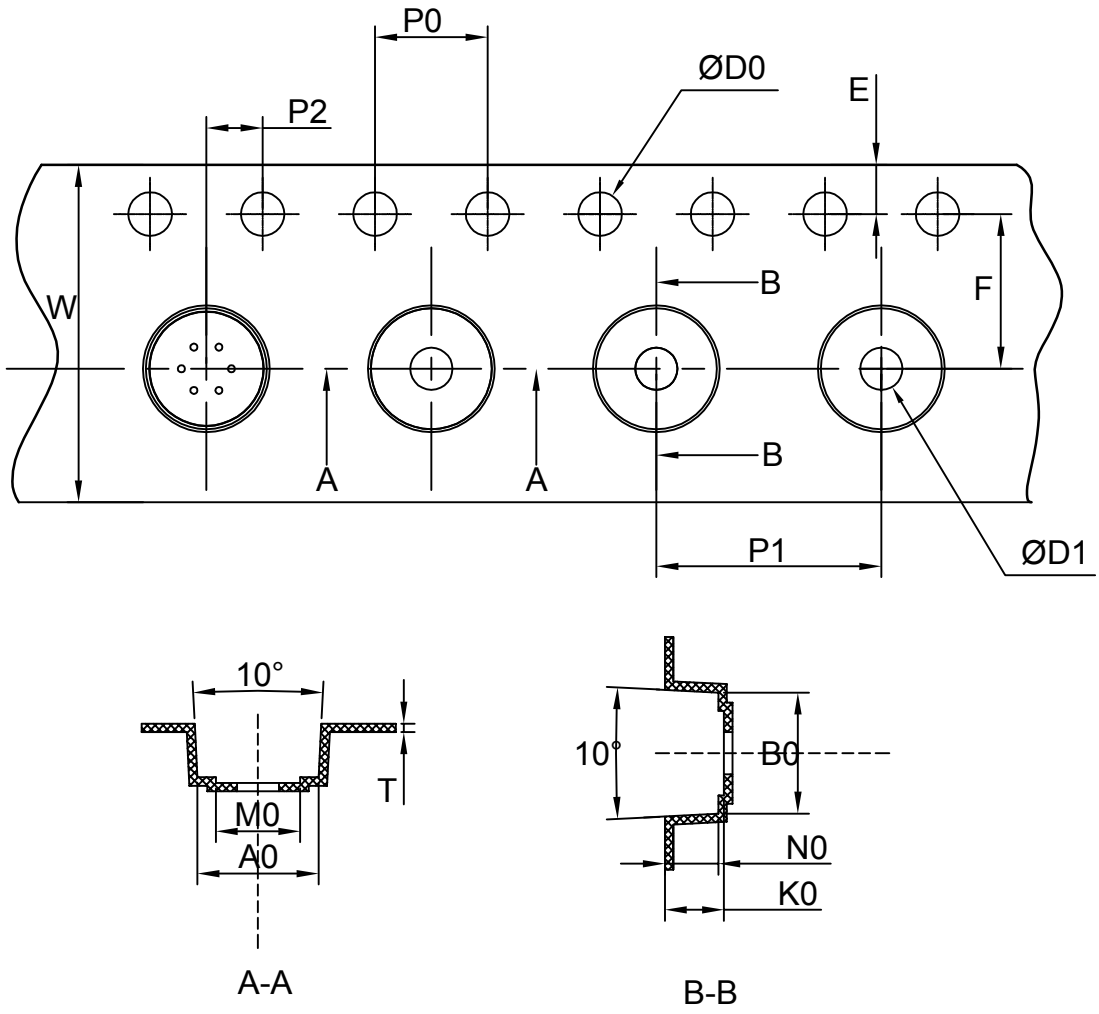
Less than 0.2g

7 Reliability Test

7.1 Vibration Test	To be no interference in operation after vibrations,10Hz to 55 Hz for 1 minute full amplitude 1.52mm,for 2 hours at three axises in state of standard packing,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.2 Drop Test	To be no interference in operation after dropped to steel plate each one time from 1.5 meter height ,12 times,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.3 Temperature Test	a) After exposure at +85°C for 200 hours,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%) b) After exposure at -40°C for 200 hours,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.4 Humidity Test	After exposure at +60°C and 90~95% relative humidity for 200 hours,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.5 Temperature Cycle Test	After exposure at -40°C for 30 minutes, at 20°C for 10 minutes, at+85°c for 30 minutes,at 20°C for 10 minutes,5 cycles,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.6 Temperature Shock Test	After exposure at -40℃ for 60 minutes, at+85℃ for 60 minutes(change time 20 seconds)，32 cycles,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)
7.7 ESD Shock Test	The microphone under test must be discharged between each ESD exposure without ground. (contact:±8kV,air:±15kV) There is no interference in operation after 10 times exposure.
7.8 Reflow Test	Adopt the reflow curve of item11.3,after two reflows,sensitivity to be within ±3dB from initial sensitivity. (The measurement to be done after 2 hours of conditioning at +15 ℃～+35℃, R.H 25%～75%)

8 Package

8.1 Taping Specification



the dimensions as follows:

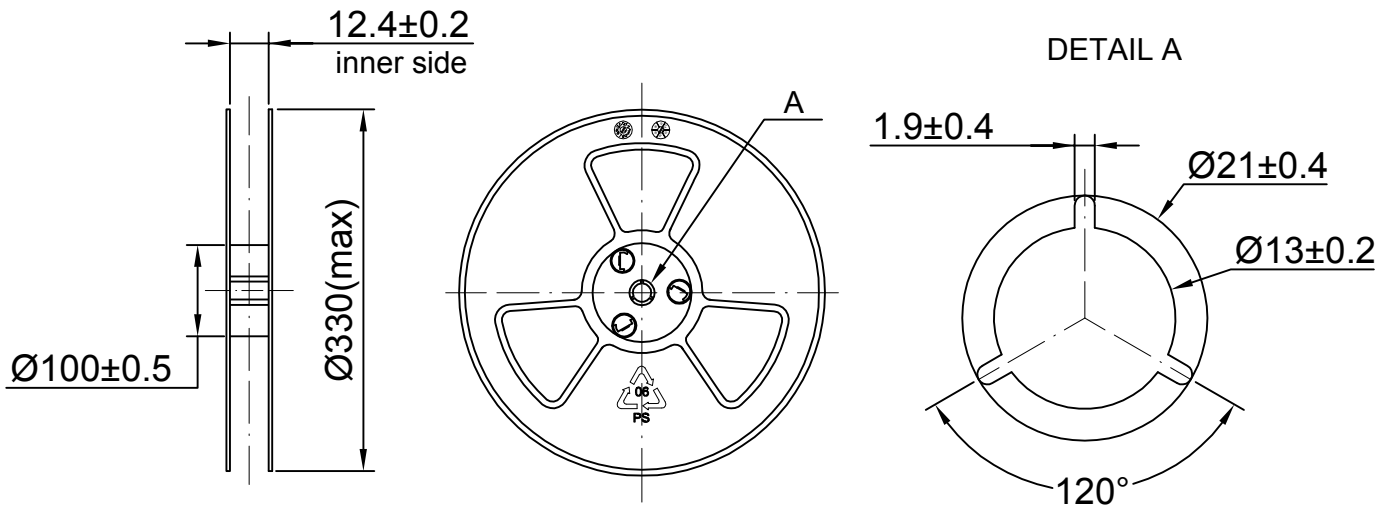
ITEM	W	E	F	ØD0	ØD1
DIM(mm)	12.0±0.30	1.75±0.10	5.50±0.05	1.50±0.10	1.55±0.10
ITEM	P0	10P0	P1	A0	B0
DIM(mm)	4.00±0.10	40.00±0.20	8.00±0.10	4.20±0.05	4.20±0.05
ITEM	K0	P2	T	M0	N0
DIM(mm)	1.70±0.10	2.00±0.05	0.35±0.05	3.00±0.05	1.50±0.1

8.2 Reel Dimension

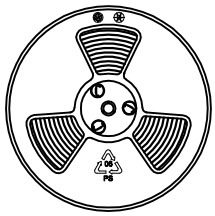
7〃 reel for sample stage

13〃 reel will be provided for the mass production stage

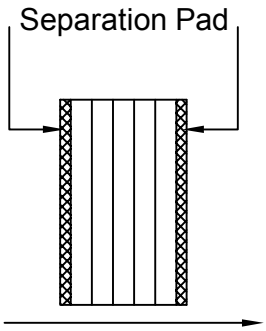
The following is 13" reel dimensions (unit:mm)



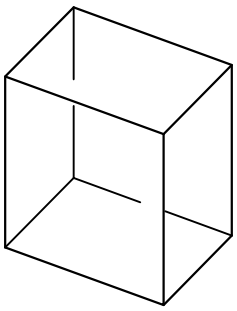
8.3 The content of box(13" reel)



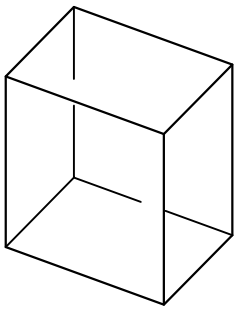
Packing (4000PCS)



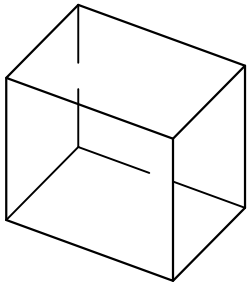
5 pcs reels



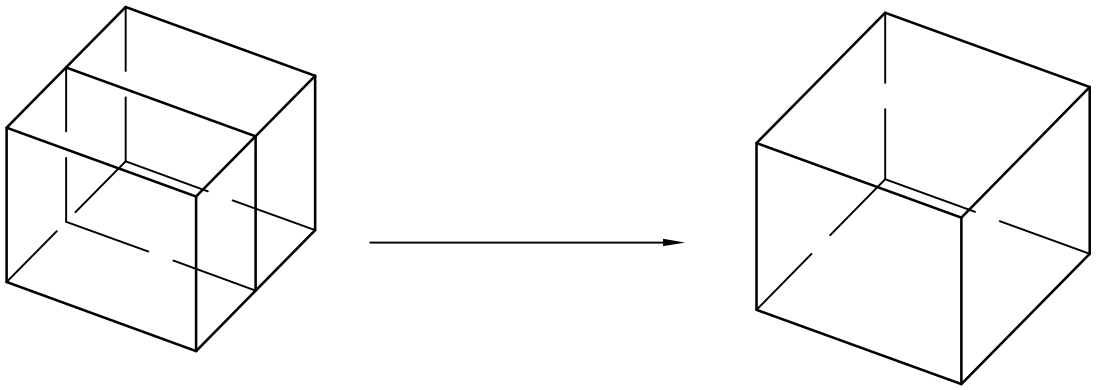
Plastic Bag (20000PCS)
(336mm*115mm*450mm)



Plastic Bag (20000PCS)
(336mm*115mm*450mm)



Inner Box (20000PCS)
(340mm*135mm*355mm)

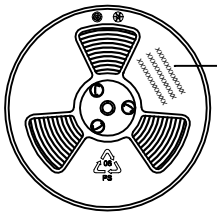


Two Inner Box(40000PCS)

Outer Box(40000PCS)
(370mm*300mm*390mm)

8.4 Packing Explain

The label content of the reel



the content including:
product type, Lot, customer P/N;
and other essential information such as Quantity, Date;
RoHS & HF compliance mark etc.

9 Stock and Transportation

9.1 Keep ECM in warehouse with less than 75% humidity and without sudden temperature change, acid air, any other harmful air or strong magnetic field.

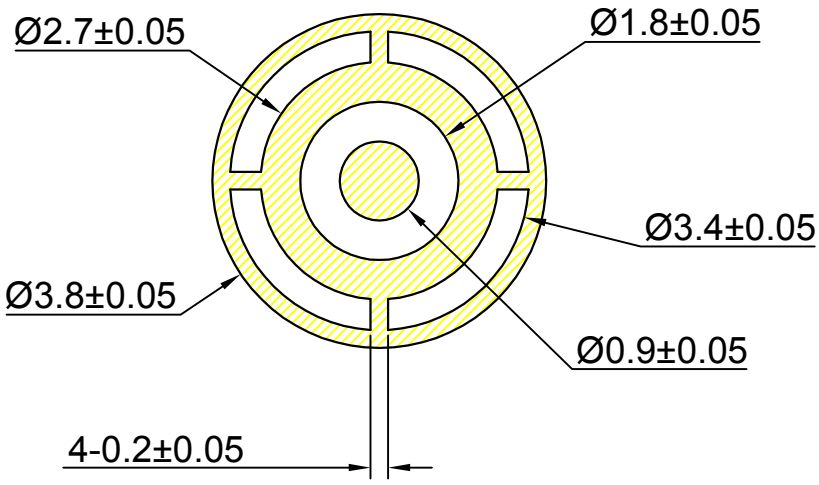
9.2 The ECM with normal pack can be transported by ordinary conveyances. Please protect products against moist, shock, sunburn and pressure during transportation.

9.3 Storage Temperature Range: -40℃~+85℃

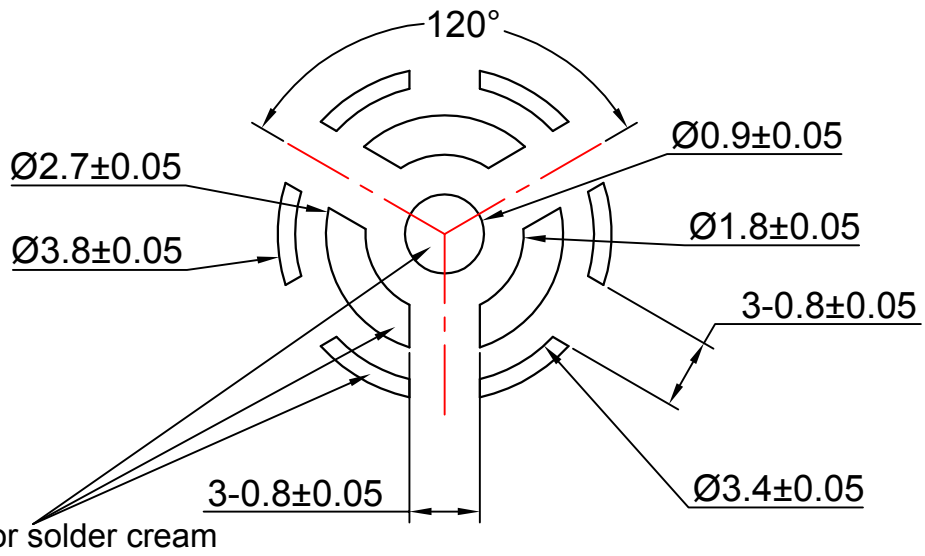
9.4 Operating Temperature Range: -30℃~+70℃

10 Land Pattern Recommendation (Unit: mm)

10.1 Soldering Surface - Land Pattern



10.2 Metal Mask Pattern



Opening for solder cream

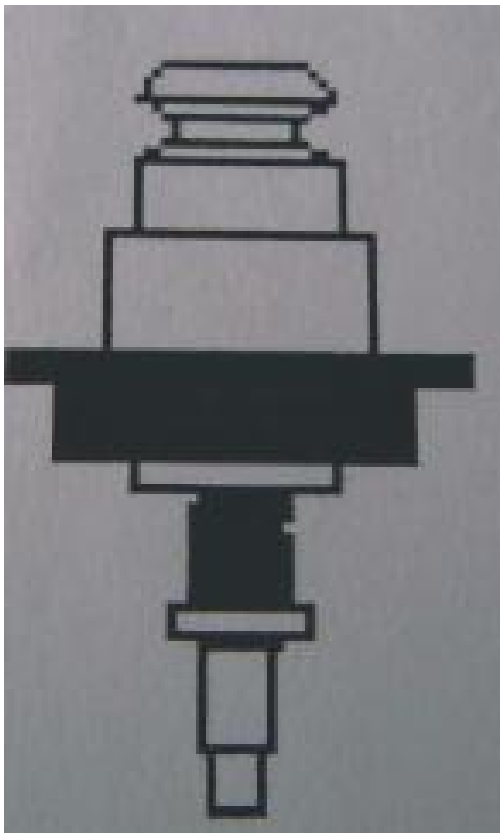
- thickness of metal mask:0.1mm

11 Recommend Soldering

11.1 Soldering Machine Condition

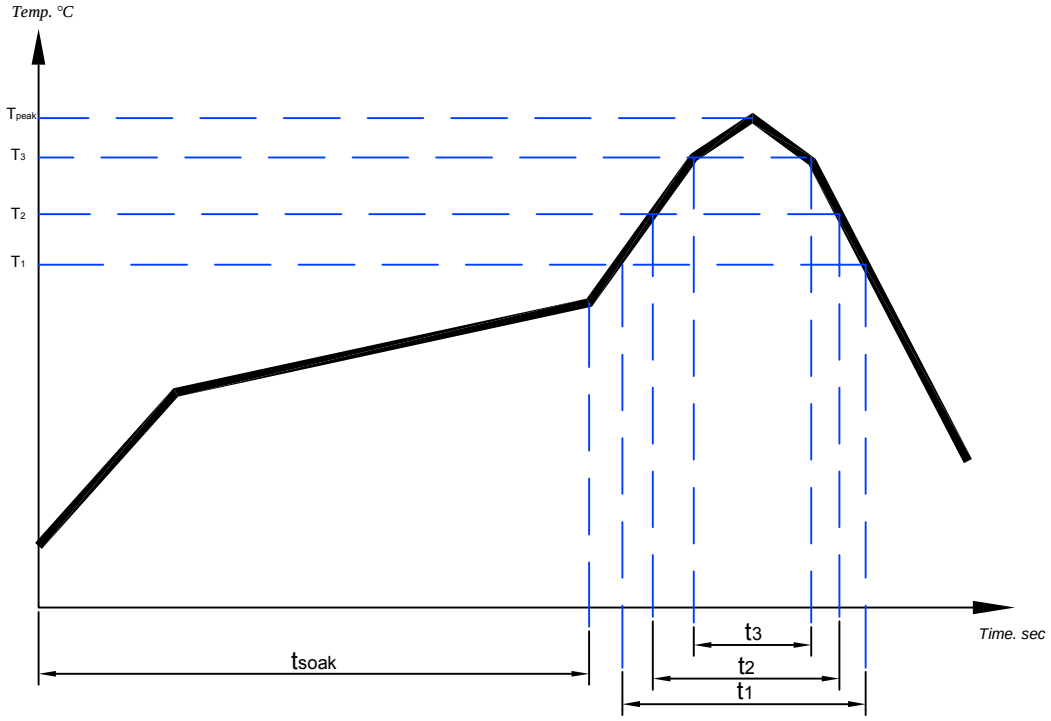
Temperature control	8 zones
Heater Type	Hot Air
Solder Type	Lead-free

11.2 The pattern of the nozzle



dimension of nozzle:504
external diameter: 1.5mm;
inside diameter: 1.0mm;
Pick up position:bottom border of microphone

11.3 Reflow Profile



Pb-free reflow profile requirements for soldering heat resistance

Parameter	Reference	Specification
Average Temperature Gradient in Preheating	---	2.5℃/s
Soak Time	t_{soak}	2-3 Minutes
Time Above 217℃	t_1	Max 60s
Time Above 230℃	t_2	Max 50s
Time Above 250℃	t_3	Max 10s
Peak Temperature In Reflow	T_{peak}	255℃ (-0/+5℃)
Temperature Gradient In Cooling	---	Max -5℃/s

When SMD MIC is soldered on PCB, the reflow profile is set according to solder paste and the thickness of PCB etc.

12 Cautions when using SMD MIC

12.1 X-ray inspection

The microphone should not be subjected to X-ray inspection. If it is absolutely necessary to do inspection using X-ray, the setting conditions with the following conditions:

Distance: >0.08meter;
Current: <0.080mA;
Time: <30s;
Voltage: <80kV.

12.2 Board wash restrictions

It is very important not to wash the PCBA after reflow process, or this could damage the microphone.

12.3 Nozzle restrictions

It is very important not to pull a nozzle over the post hole of the microphone. or this could damage the microphone.

12.4 Others restrictions

The pressure on the MIC shouldn't be more than 10N; The connecting between the institution and MIC should use rubber or Poron.

13 Output Inspection standard

output inspection standard is excuted according to <<ISO2859-1:1999>>.